



IT-859GTABS/IT-859GTA

Multifunctional Filled Epoxy / Lead Free / Metal Base Laminate & Prepreg

- Middle Thermal Conductivity
- Excellent Thermal Shock and Dielectric Properties

Laminate properties

| Items | IPC TM-650 | Typical Value | Unit |
|--|------------|--------------------|-------------------|
| Peel Strength, minimum | | | |
| A. Low profile copper foil | 2.4.8 | 4.0~5.0 | lb/inch |
| B. Standard profile copper foil | | 6.0~7.0 | |
| Volume Resistivity | 2.5.17.1 | > 10 ¹⁰ | MΩ-cm |
| Surface Resistivity | 2.5.17.1 | > 10 ¹⁰ | MΩ |
| Moisture Absorption, maximum | 2.6.2.1 | < 0.1 | % |
| Permittivity at 1MHz,maximun (laminate & Laminated Prepreg) | 2.5.5.13 | 4.8 | -- |
| Loss Tangent at 1MHz,maximun (laminate & Laminated Prepreg) | 2.5.5.13 | 0.018 | -- |
| Flexural Strength, minimum | | | |
| A. Length direction | 2.4.4 | 415-480 | N/mm ² |
| B. Cross direction | | 345~450 | |
| Thermal Stress 10 s at 288°C | | | |
| A. Unetched | 2.4.13.1 | Pass | Rating |
| B. Etched | | Pass | |
| Flammability | UL94 | N/A | Rating |
| Glass Transition Temperature(DSC) | 2.4.25 | 100 | °C |
| Decomposition Temperature | 2.4.24.6 | 380 | °C |
| X/Y Axis CTE (40°C to 125°C) | 2.4.24 | 9/11 | ppm/°C |
| Z-Axis CTE | | | |
| A. Alpha 1 | 2.4.24 | 45 | ppm/°C |
| B. Alpha 2 | | 250 | ppm/°C |
| C. 50 to 260 Degrees C | | 3.5 | % |
| Thermal Resistance | | | |
| A. T260 | 2.4.24.1 | >60 | Minutes |
| B. T288 | | >60 | Minutes |